

Wet and Dry Etching

Pre-Lab Questions

1. Which one, wet etching or dry etching, is more preferable and mostly used in the critical processes of semiconductor manufacturing? Why? What are the differences between wet etching and dry etching?
2. What is rate-limiting step? Describe the diffusion controlled and reaction-rate controlled processes.
3. How will you determine the activation energy of wet etching?
4. Briefly describe the mechanisms of plasma etching.
5. Explain the difference between isotropic and anisotropic etching. Which will you prefer?
6. What are safety hazards in this experiment? Briefly describe rules for prevention of these hazards.